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Filler Material, And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield

Inventor(s): Lowell E Kolb et al

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FIG. 1

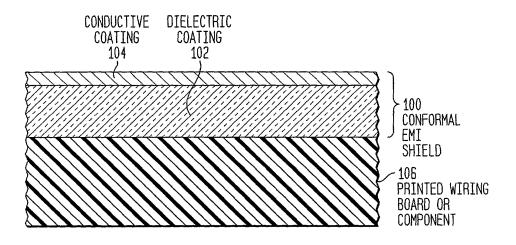
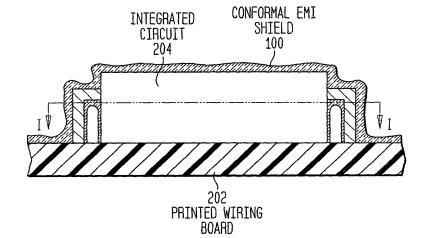


FIG. 2A



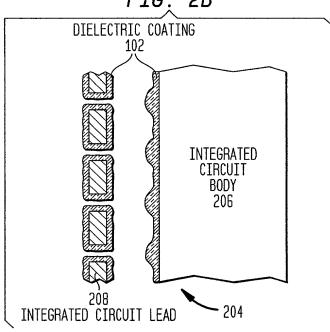
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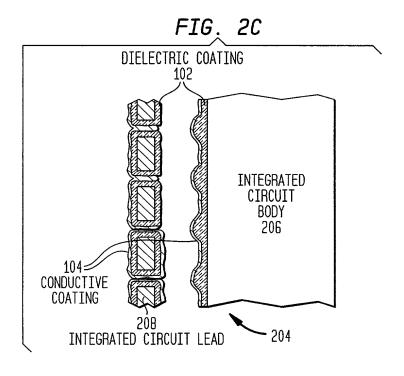
Filler Material And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield

Inventor(s): Lowell E Kolb et al

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FIG. 2B

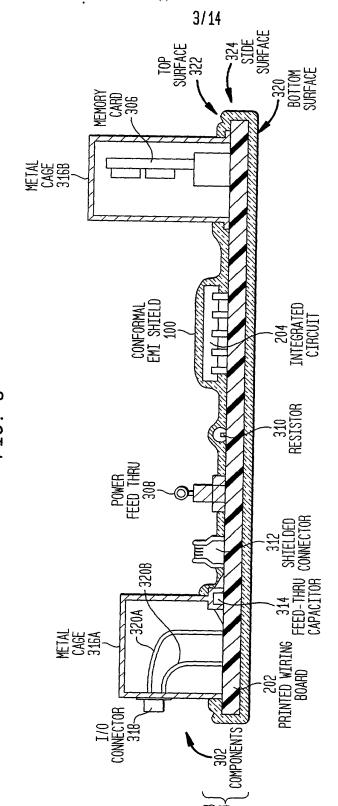




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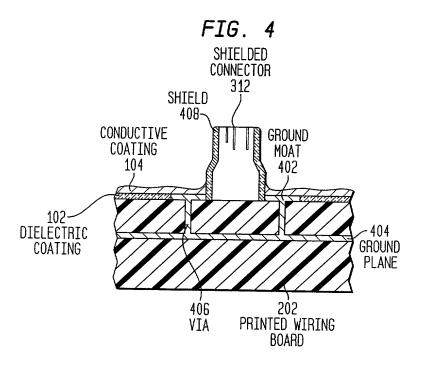
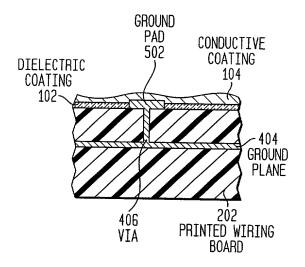


FIG. 5



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Filler Material And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield Inventor(s): Lowell E Kolb et al

FIG. 6A

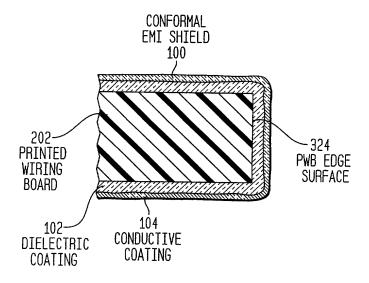
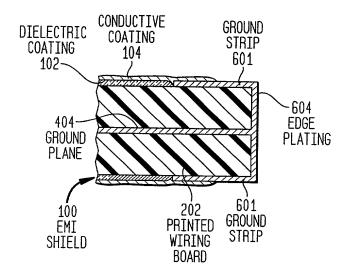


FIG. 6B



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Inventor(s): Lowell E Kolb et al

FIG. 6C

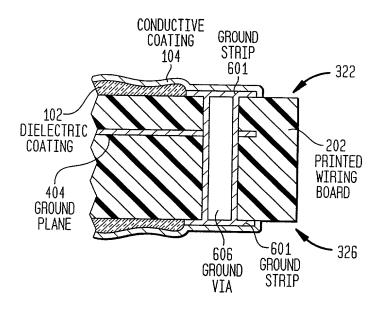
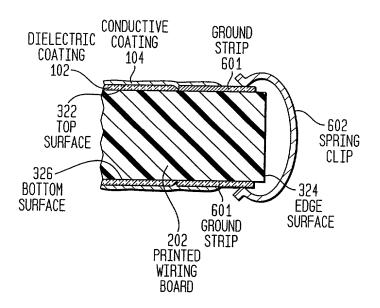


FIG. 6D



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Filler Material And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield

Inventor(s): Lowell E Kolb et al

FIG. 6E

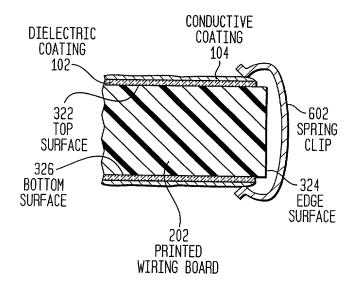
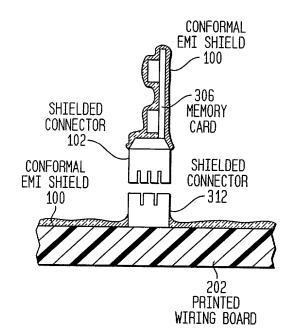


FIG. 7



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Filler Material And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield Inventor(s): Lowell E Kolb et al

FIG. 8A

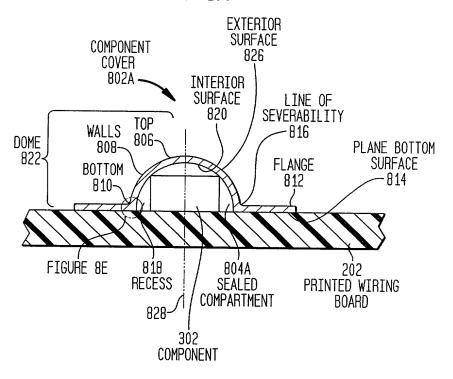


FIG. 8B

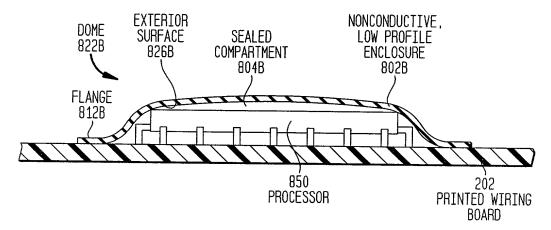
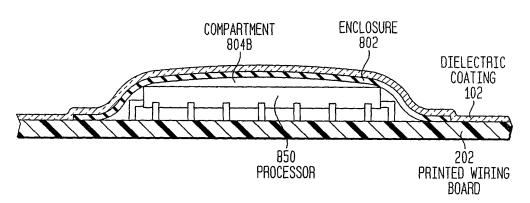
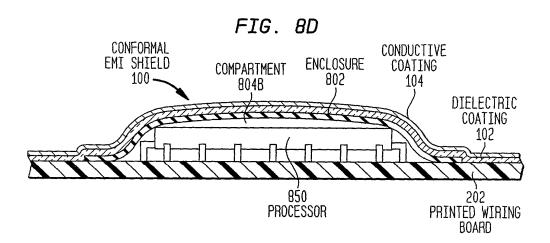


FIG. 8C





Filler Material, And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield Inventor(s): Lowell E Kolb et al 10/14

FIG. 8E-1

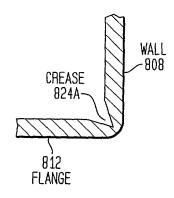
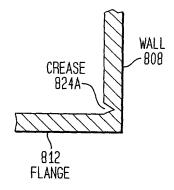


FIG. 8E-2



Filler Material And Pretreatment Of Printed Circuit Board Components To Facilitate Application Of A Conformal EMI Shield

Inventor(s): Lowell E Kolb et al

FIG. 9A

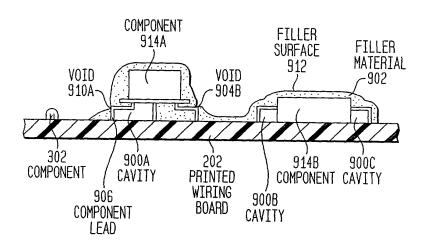


FIG. 9B

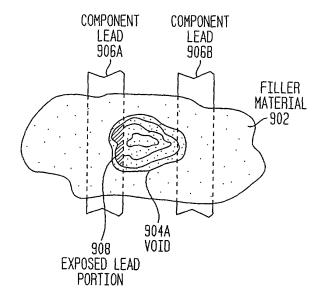


FIG. 9C

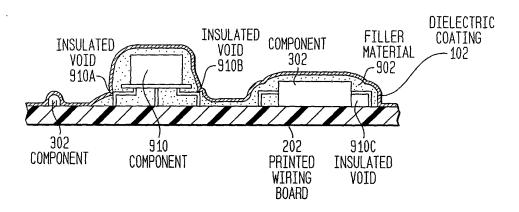
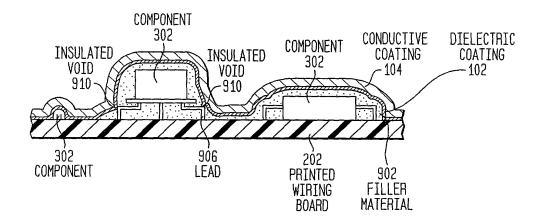


FIG. 9D



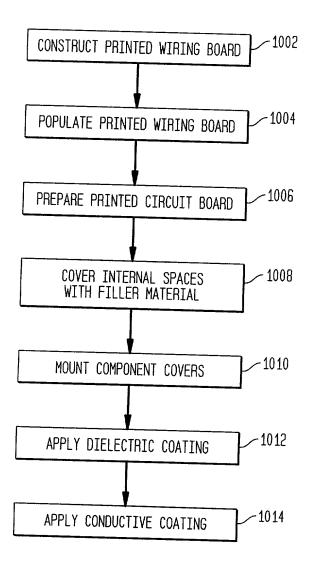
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Inventor(s): Lowell E Kolb et al

FIG. 10



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FIG. 11

